Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

• ISO-9001
• AS9120 certification
• Qualified Manufacturers List (QML) MIL-PRF-35835
    • Class Q Military
    • Class V Space Level
• Qualified Suppliers List of Distributors (QSLD)

    • Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FAIRCHILD

SEMICONDUCTOR®

74ABT162244
16-Bit Buffer/Line Driver with 25Ω Series Resistors in the Outputs

General Description

The ABT162244 contains sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Individual 3-STATE control inputs can be shorted together for 8-bit or 16-bit operation.

The 25Ω series resistors in the outputs reduce ringing and eliminate the need for external resistors.

Features

■ Separate control logic for each nibble

■ 16-bit version of the ABT2244

■ Guaranteed latchup protection

■ High impedance glitch free bus loading during entire power up and power down cycle

■ Non-destructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT162244CSSC	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [RAIL]
74ABT162244CSSX	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [TAPE and REEL]
74ABT162244CMTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [RAIL]
74ABT162244MTDX	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [TAPE and REEL]

Logic Symbol
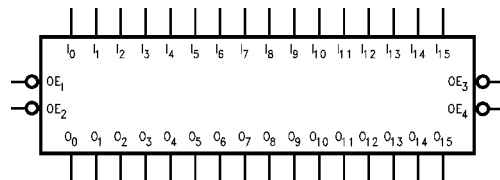
Connection Diagram
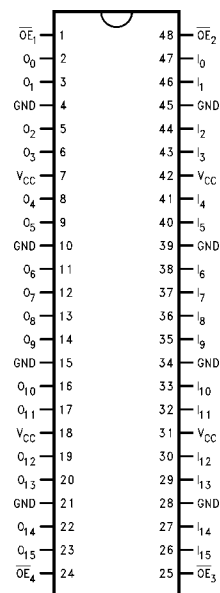
Pin Descriptions

Pin Names	Description
$\overline{OE}_n$	Output Enable Input (Active LOW)
$I_0–I_{15}$	Inputs
$O_0–O_{15}$	Outputs

Truth Tables

Inputs		Outputs
$\overline{OE}_1$	I_0–I_3	O_0–O_3
L	L	L
L	H	H
H	X	Z

Inputs		Outputs
$\overline{OE}_3$	I_8–I_{11}	O_8–O_{11}
L	L	L
L	H	H
H	X	Z

Inputs		Outputs
$\overline{OE}_2$	I_4–I_7	O_4–O_7
L	L	L
L	H	H
H	X	Z

Inputs		Outputs
$\overline{OE}_4$	I_{12}–I_{15}	O_{12}–O_{15}
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
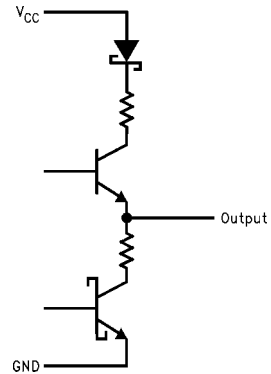X = Immaterial
Z = High Impedance

Functional Description

The ABT162244 contains sixteen non-inverting buffers with 3-STATE outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation.

Logic Diagram
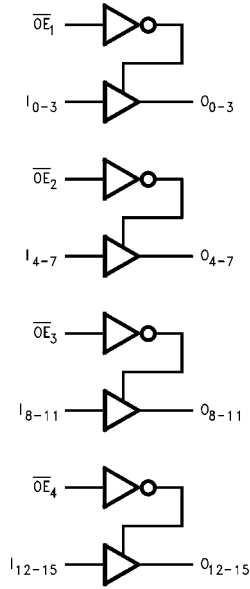
Schematic of each Output

Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Any Output	
in the Disabled or	
Power-Off State	−0.5V to 5.5V
in the HIGH State	−0.5V to V_{CC}
Current Applied to Output	
in LOW State (Max)	twice the rated I_{OL} (mA)
DC Latchup Source Current	−500 mA
Over Voltage Latchup (I/O)	10V

Recommended Operating Conditions

Free Air Ambient Temperature	−40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate ($\Delta V/\Delta t$)	
Data Input	50 mV/ns
Enable Input	20 mV/ns

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	$I_{IN} = -18$ mA
V_{OH}	Output HIGH Voltage		2.5			V	Min	$I_{OH} = -3$ mA
			2.0			V	Min	$I_{OH} = -32$ mA
V_{OL}	Output LOW Voltage				0.8	V	Min	$I_{OL} = 12$ mA
I_{IH}	Input HIGH Current				1	μA	Max	$V_{IN} = 2.7$V (Note 3)
					1			$V_{IN} = V_{CC}$
I_{BVI}	Input HIGH Current Breakdown Test				7	μA	Max	$V_{IN} = 7.0$V
I_{IL}	Input LOW Current				−1	μA	Max	$V_{IN} = 0.5$V (Note 3)
					−1			$V_{IN} = 0.0$V
V_{ID}	Input Leakage Test		4.75			V	0.0	$I_{ID} = 1.9$ μA
								All Other Pins Grounded
I_{OZH}	Output Leakage Current				10	μA	0 – 5.5V	$V_{OUT} = 2.7$V; $\overline{OE}_n = 2.0$V
I_{OZL}	Output Leakage Current				−10	μA	0 – 5.5V	$V_{OUT} = 0.5$V; $\overline{OE}_n = 2.0$V
I_{OS}	Output Short-Circuit Current		−100		−275	mA	Max	$V_{OUT} = 0.0$V
I_{CEX}	Output High Leakage Current				50	μA	Max	$V_{OUT} = V_{CC}$
I_{ZZ}	Bus Drainage Test				100	μA	0.0	$V_{OUT} = 5.5$V; All Others GND
I_{CCH}	Power Supply Current				2.0	mA	Max	All Outputs HIGH
I_{CCL}	Power Supply Current				60	mA	Max	All Outputs LOW
I_{CCZ}	Power Supply Current				2.0	mA	Max	$\overline{OE}_n = V_{CC}$ All Others at V_{CC} or GND
I_{CCT}	Additional I_{CC}/Input	Outputs Enabled			3.0	mA		$V_I = V_{CC} - 2.1$V
		Outputs 3-STATE			3.0	mA	Max	Enable Input $V_I = V_{CC} - 2.1$V
		Outputs 3-STATE			50	μA		Data Input $V_I = V_{CC} - 2.1$V All Others at V_{CC} or GND
I_{CCD}	Dynamic I_{CC} (Note 3)	No Load			0.1	mA/MHz	Max	Outputs OPEN $\overline{OE}_n = $ GND One Bit Toggling, 50% Duty Cycle

Note 3: Guaranteed, but not tested.

AC Electrical Characteristics

Symbol	Parameter	$T_A = +25°C$ $V_{CC} = +5V$ $C_L = 50$ pF			$T_A = -40°C$ to $+85°C$ $V_{CC} = 4.5V–5.5V$ $C_L = 50$ pF		Units
		Min	Typ	Max	Min	Max	
t_{PLH}	Propagation	1.0	2.4	3.9	1.0	3.9	ns
t_{PHL}	Delay Data to Outputs	1.0	3.2	4.7	1.0	4.7	
t_{PZH}	Output	1.5	3.5	6.3	1.5	6.3	ns
t_{PZL}	Enable Time	1.5	4.2	6.9	1.5	6.9	
t_{PHZ}	Output	1.0	4.2	6.7	1.0	6.7	ns
t_{PLZ}	Disable Time	1.0	3.8	6.7	1.0	6.7	

Capacitance

Symbol	Parameter	Typ	Units	Conditions $T_A = 25°C$
C_{IN}	Input Capacitance	5.0	pF	$V_{CC} = 0.0V$
C_{OUT} (Note 4)	Output Capacitance	9.0	pF	$V_{CC} = 5.0V$

Note 4: C_{OUT} is measured at frequency f = 1 MHz per MIL-STD-883, Method 3012.

AC Loading

FIGURE 1. Standard AC Test Load
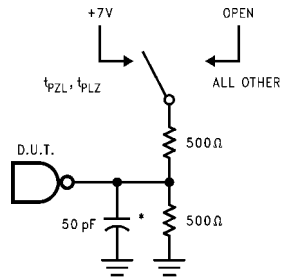
*Includes jig and probe capacitance
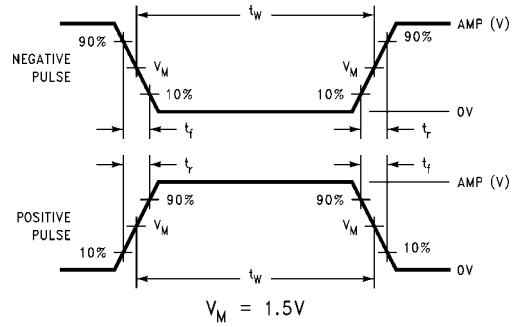
FIGURE 2. Input Pulse Requirements

$V_M = 1.5V$

Amplitude	Rep. Rate	t_W	t_r	t_f
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

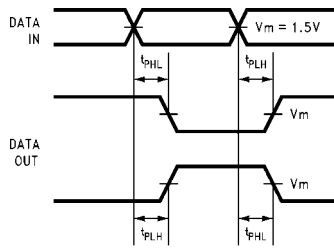**FIGURE 3. Test Input Signal Requirements**

AC Waveforms

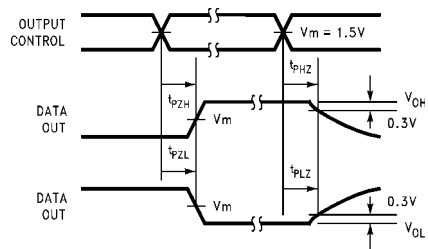**FIGURE 4. Propagation Delay Waveforms for Inverting and Non-Inverting Functions**

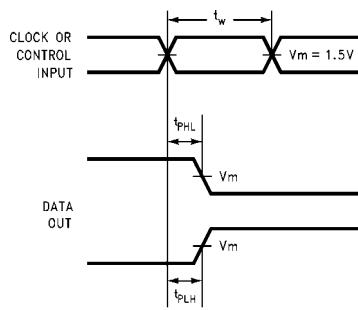**FIGURE 6. 3-STATE Output HIGH and LOW Enable and Disable Times**
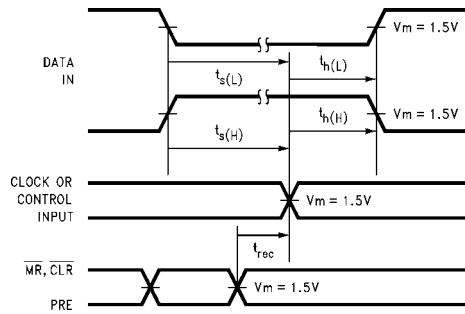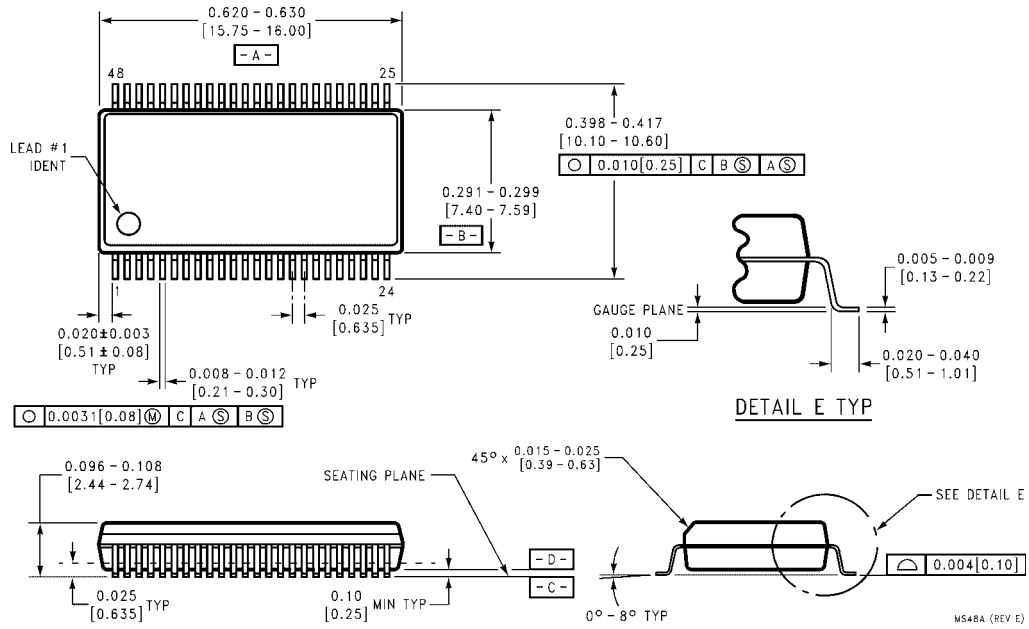
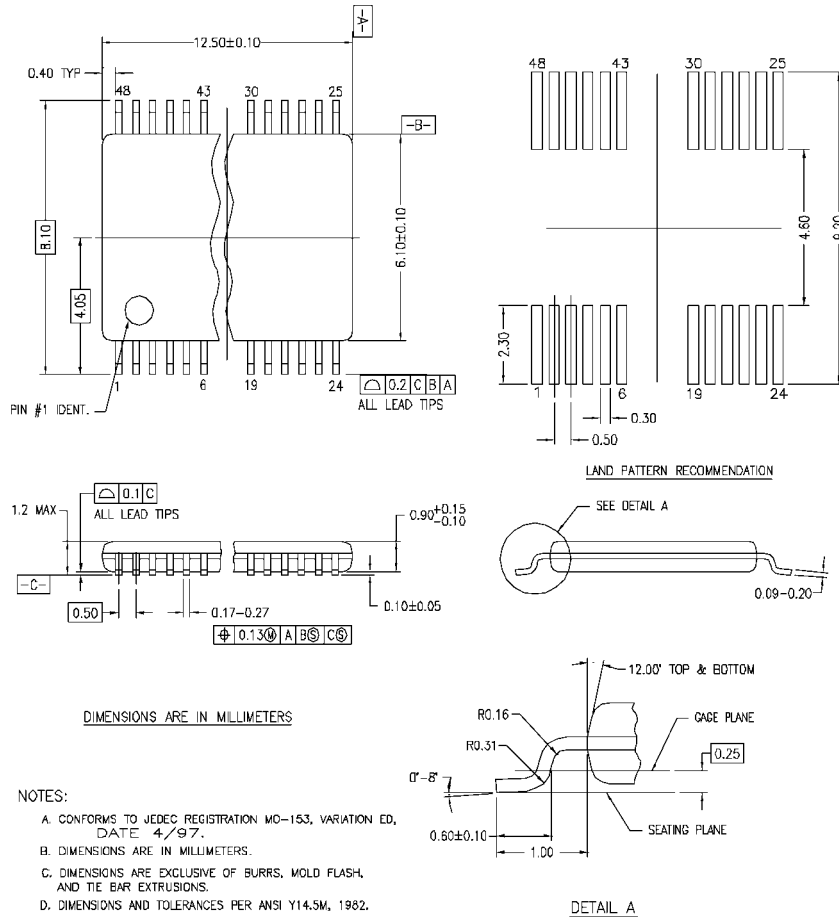**FIGURE 5. Propagation Delay, Pulse Width Waveforms**

FIGURE 7. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted

0.620 – 0.630
[15.75 – 16.00]
– A –

48   25

LEAD #1
IDENT

0.398 – 0.417
[10.10 – 10.60]
○ | 0.010[0.25] | C | B Ⓢ | A Ⓢ |

0.291 – 0.299
[7.40 – 7.59]
– B –

1   24

0.025
[0.635] TYP

0.020±0.003
[0.51 ± 0.08]
TYP

0.008 – 0.012
[0.21 – 0.30] TYP

○ | 0.0031[0.08]Ⓜ | C | A Ⓢ | B Ⓢ |

GAUGE PLANE

0.010
[0.25]

0.005 – 0.009
[0.13 – 0.22]

0.020 – 0.040
[0.51 – 1.01]

DETAIL E TYP

0.096 – 0.108
[2.44 – 2.74]

SEATING PLANE

45° x 0.015 – 0.025
[0.39 – 0.63]

SEE DETAIL E

– D –
– C –

0.025
[0.635] TYP

0.10
[0.25] MIN TYP

0° – 8° TYP

△ | 0.004[0.10] |

MS48A (REV E)

**48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
Package Number MS48A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS ARE IN MILLIMETERS

NOTES:
A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTD48REVC

**48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide
Package Number MTD48**

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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